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**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claim 1 (canceled)

Claim 2 (currently amended): A method of manufacturing a nonreciprocal circuit device ~~comprising a metal case covering central conductors, a ferrite core arranged near the central conductors, and a permanent magnet for applying a static magnetic field to the ferrite core~~, the method comprising the steps of:

providing a metal case covering central conductors, a ferrite core arranged near the central conductors, and a permanent magnet for applying a static magnetic field to the ferrite core;

marking information onto the metal case by irradiating the metal case with a laser beam; and

heating the nonreciprocal circuit device after the information has been marked onto the metal case.

Claim 3 (previously presented): The method of manufacturing a nonreciprocal circuit device according to Claim 2, further comprising magnetizing or demagnetizing the permanent magnet to adjust a magnetic force of the permanent magnet prior to the heating step.

Claim 4 (original): The method of manufacturing a nonreciprocal circuit device according to Claim 2, wherein the heating step both r moves stains caused by the laser

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marking and thermally demagnetizes the permanent magnet.

Claim 5 (original): The method of manufacturing a nonreciprocal circuit device according to Claim 2, wherein the heating temperature in the heating step is set between 110° and 210°C.

Claim 6 (original): The method of manufacturing a nonreciprocal circuit device according to Claim 2, further comprising applying solder paste to portions where the components comprising the nonreciprocal circuit device are bonded with each other, prior to the heating step.

Claim 7 (original): The method of manufacturing a nonreciprocal circuit device according to Claim 6, wherein the heating temperature in the heating step is set between 210° and 310°C.

Claim 8 (previously presented): The method of manufacturing a nonreciprocal circuit device according to Claim 2, wherein the metal case comprises an upper yoke and a lower yoke and the laser marking is performed onto the upper yoke before the upper and lower yokes are bonded with each other.

Claim 9 (previously presented): The method of manufacturing a nonreciprocal circuit device according to Claim 2, wherein the laser marking is performed by continuously irradiating a laser beam onto the metal case.

Claim 10 (previously presented): The method of manufacturing a nonreciprocal circuit device according to Claim 2, wherein the laser marking is performed by irradiating the metal case with a pulsed laser beam.

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Claim 11 (previously presented): The method of manufacturing a nonreciprocal circuit device according to Claim 2, wherein the laser beam has a wavelength of 10  $\mu\text{m}$  or less.

Claim 12 (previously presented): The method of manufacturing a nonreciprocal circuit device according to Claim 2, wherein the used laser is a YAG laser or a  $\text{YVO}_4$  laser.

Claims 13-17 (canceled).